

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Title: METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER,
GOLD, AND OTHER METALS

Docket No.: 303.648US1

Serial No.: 09/484,303

Filed: January 18, 2000

Due Date: N/A

Examiner: William D Coleman

Group Art Unit: 2823

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):


☒ Communication Concerning Related Applications (2 pgs.).

☒ Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.


Customer Number 21186

By: 
Atty: Timothy B. Clise
Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 19th day of September, 2006.

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Name


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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)

S/N 09/484,303

PATENT

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Serial No.:	09/484,303	Group Art Unit:	2823
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COMMUNICATION CONCERNING RELATED APPLICATION(S)

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Applicants would like to bring to the Examiner's attention the following related application(s)
in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10929251	August 30, 2004	303.672US2	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION
10931541	August 31, 2004	303.648US2	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
11457099	July 12, 2006	303.648US3	METHOD FOR MAKING INTEGRATED CIRCUITS
11458975	July 20, 2006	303.648US4	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
11458195	July 18, 2006	303.664US6	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

KIE Y. AHN ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

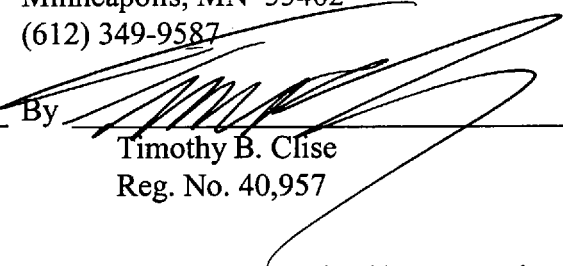
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Date

18 Sept '06

By

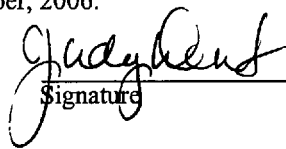

Timothy B. Clise

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